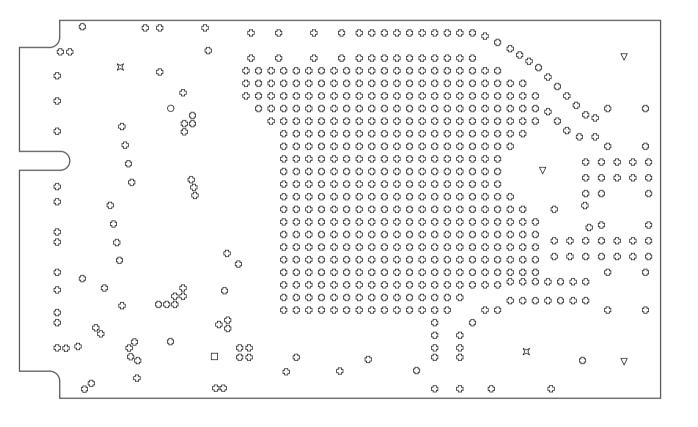
Used material — S1000H Stack-Up Number of layers - 4 Silkscreen Top Soldermask Top Board thickness - 1.0mm +/-10% Copper Plating Layer 1 (43um) Thickness of outer layer (Cu) — 43um include copper plating S1000H 1x3313 - 100um Core Layer 2 (18um) Thickness of inner layers (Cu) - 18um Prepreg S1000HB 7628 (46) - 195um Core S1000H 2x1506 - 300um Solder Mask - Two sides, Green Prepreg S1000HB 7628 (46) - 195um Layer 3 (18um) S1000H 1x3313 - 100um Core Silkscreen - No Layer 4 (43um) Copper Plating Type of coating - ENIG Soldermask Top Silkscreen Top Edge Connector - Hard Gold Au 0,2-0,5um/Ni 5um 10. Electrical Test on both side (use Adapter_MPCle_to_M2_E.ipc file) 11. Min dia of plated hole - 0.2mm 12. Min trace width/clearance - 0.1mm/0.1mm 13. Impedance control — Yes, see details 14. Impedance tolerance - 10% 15. Board dimensions - 50.95mm x 30mm

0.15±0.05 mm



Impedance Requirement Table

Typo	Layer	Ref. Layer		Trace	Trace	Ground	Impodance
Туре		Upper	Lower	Width	Separation	Spacing	Impedance
Differential	1	1	2	0.150	_	0.300	50 Ohm
Differential	4	1	3	0.135	0.155	1	90 Ohm
Differential	1	1	2	0.110	0.170	_	100 Ohm

Symbol	Hole Size	Plated	Drill Layer Pair	Count
Ç	0.200mm	PTH	01_Top - 04_Bottom	585
	1.100mm	NPTH	01_Top - 04_Bottom	1
0	1.600mm	NPTH	01_Top - 04_Bottom	1
∇	2.600mm	PTH	01_Top - 04_Bottom	3
\bowtie	3.200mm	NPTH	01_Top — 04_Bottom	2